General Purpose Transistor

NPN Silicon

Features

• Pb-Free Package is Available

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	45	Vdc
Collector-Base Voltage	V _{CBO}	50	Vdc
Emitter-Base Voltage	V _{EBO}	5.0	Vdc
Collector Current – Continuous	Ι _C	100	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW m₩/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) $T_A = 25^{\circ}C$ Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

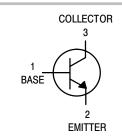
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in. 2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.



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SOT-23 (TO-236) **CASE 318 STYLE 6**

MARKING DIAGRAM



K2 = Device Code

М = Date Code*

= Pb-Free Package •

(Note: Microdot may be in either location) *Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

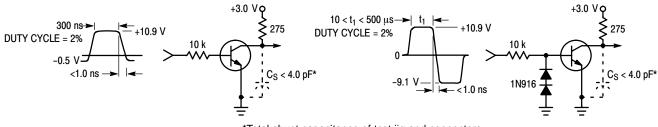
Device	Package	Shipping [†]
BCW72LT1	SOT-23	3,000 / Tape & Reel
BCW72LT1G	SOT–23 (Pb–Free)	3,000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage $(I_C = 2.0 \text{ mAdc}, V_{EB} = 0)$	V _{(BR)CEO}	45	_	_	Vdc
Collector – Emitter Breakdown Voltage $(I_C = 2.0 \text{ mAdc}, V_{EB} = 0)$	V _{(BR)CES}	45	_	_	Vdc
Collector – Base Breakdown Voltage $(I_C = 10 \ \mu Adc, I_E = 0)$	V _{(BR)CBO}	50	_	_	Vdc
Emitter – Base Breakdown Voltage $(I_E = 10 \ \mu Adc, I_C = 0)$	V _{(BR)EBO}	5.0	_	_	Vdc
Collector Cutoff Current $(V_{CB} = 20 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 20 \text{ Vdc}, I_E = 0, T_A = 100^{\circ}\text{C})$	I _{СВО}			100 10	nAdc μAdc
ON CHARACTERISTICS					
DC Current Gain ($I_C = 2.0 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc}$)	h _{FE}	200	-	450	-
Collector – Emitter Saturation Voltage $(I_C = 10 \text{ mAdc}, I_B = 0.5 \text{ mAdc})$ $(I_C = 50 \text{ mAdc}, I_B = 2.5 \text{ mAdc})$	V _{CE(sat)}		_ 0.21	0.25	Vdc
Base – Emitter Saturation Voltage $(I_C = 50 \text{ mAdc}, I_B = 2.5 \text{ mAdc})$	V _{BE(sat)}	_	0.85	_	Vdc
Base – Emitter On Voltage $(I_C = 2.0 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc})$	V _{BE(on)}	0.6	_	0.75	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Current-Gain – Bandwidth Product ($I_C = 10 \text{ mAdc}, V_{CE} = 5.0 \text{ Vdc}, f = 100 \text{ MHz}$)	f _T	_	300	_	MHz
Output Capacitance ($I_E = 0$, $V_{CB} = 10$ Vdc, f = 1.0 MHz)	C _{obo}	_	_	4.0	pF
Input Capacitance ($I_E = 0$, $V_{CB} = 10$ Vdc, f = 1.0 MHz)	C _{ibo}	_	9.0	_	pF
Noise Figure (I _C = 0.2 mAdc, V _{CE} = 5.0 Vdc, R _S = 2.0 k Ω , f = 1.0 kHz, BW = 200 Hz)	NF	_	_	10	dB

EQUIVALENT SWITCHING TIME TEST CIRCUITS



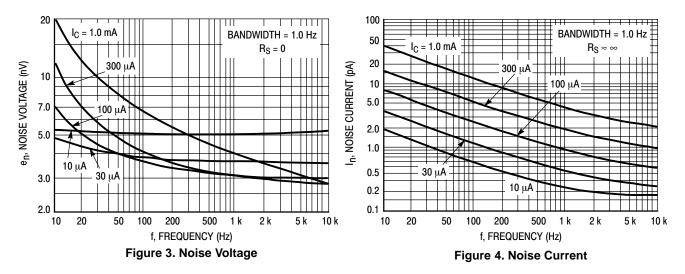
*Total shunt capacitance of test jig and connectors

Figure 1. Turn–On Time

Figure 2. Turn-Off Time

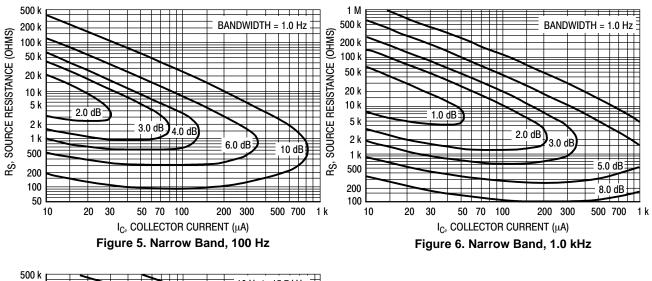


 $(V_{CE} = 5.0 \text{ Vdc}, \text{ } T_{A} = 25^{\circ}\text{C})$



NOISE FIGURE CONTOURS

 $(V_{CE} = 5.0 \text{ Vdc}, T_A = 25^{\circ}C)$



10 Hz to 15.7 kHz 200 k SOURCE RESISTANCE (OHMS) 100 k 50 k 20 k 10 k 5 k .0 dB 2 k 2.0 dB 1 k 3.0 dB 500 5.0 dB ЪŜ, 200 8.0 dB + 100 50 10 20 30 50 70 100 200 300 500 700 1 k I_C, COLLECTOR CURRENT (μA) Figure 7. Wideband

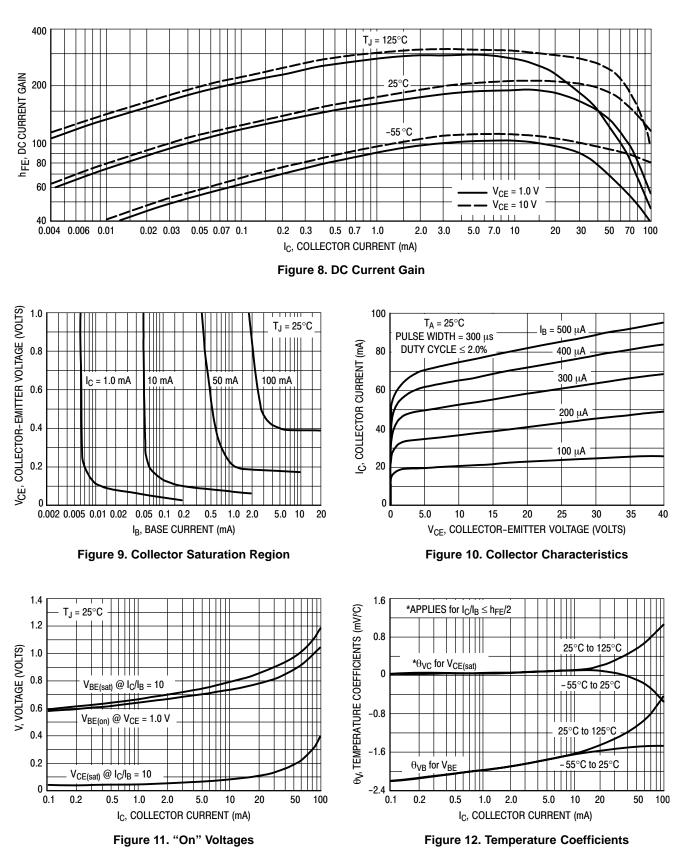
Noise Figure is defined as:

$$NF = 20 \log_{10} \left(\frac{e_{n}^{2} + 4KTR_{S} + I_{n}^{2}R_{S}^{2}}{4KTR_{S}} \right)^{1/2}$$

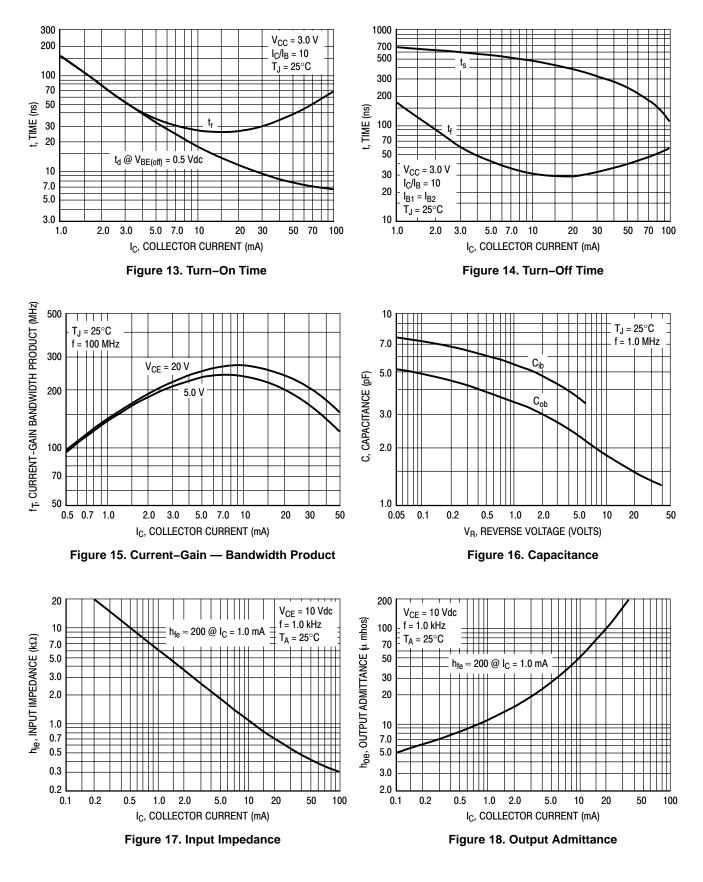
en = Noise Voltage of the Transistor referred to the input. (Figure 3)

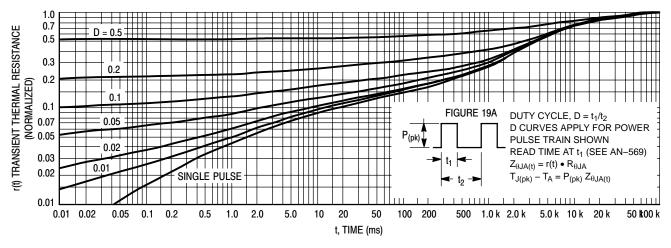
- I_n = Noise Current of the Transistor referred to the input. (Figure 4)
- K = Boltzman's Constant (1.38 x 10⁻²³ j/°K)
- T = Temperature of the Source Resistance ($^{\circ}$ K)
- R_S = Source Resistance (Ohms)

TYPICAL STATIC CHARACTERISTICS



TYPICAL DYNAMIC CHARACTERISTICS







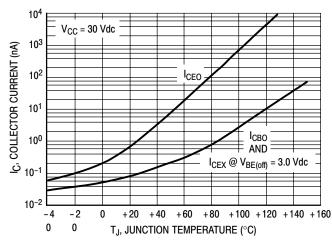


Figure 19A.

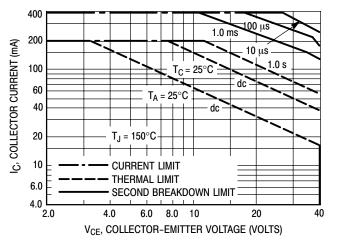


Figure 20.

DESIGN NOTE: USE OF THERMAL RESPONSE DATA

A train of periodical power pulses can be represented by the model as shown in Figure 19A. Using the model and the device thermal response the normalized effective transient thermal resistance of Figure 19 was calculated for various duty cycles.

To find $Z_{\theta JA(t)}$, multiply the value obtained from Figure 19 by the steady state value $R_{\theta JA}$.

Example:

The MPS3904 is dissipating 2.0 watts peak under the following conditions:

 $t_1 = 1.0 \text{ ms}, t_2 = 5.0 \text{ ms}. (D = 0.2)$

Using Figure 19 at a pulse width of 1.0 ms and D = 0.2, the reading of r(t) is 0.22.

The peak rise in junction temperature is therefore

 $\Delta T = r(t) \times P_{(pk)} \times R_{\theta JA} = 0.22 \times 2.0 \times 200 = 88^{\circ}C.$

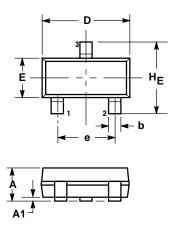
For more information, see AN-569.

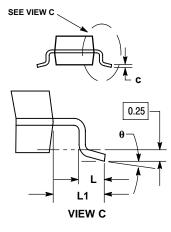
The safe operating area curves indicate I_C-V_{CE} limits of the transistor that must be observed for reliable operation. Collector load lines for specific circuits must fall below the limits indicated by the applicable curve.

The data of Figure 20 is based upon $T_{J(pk)} = 150^{\circ}C; T_C \text{ or } T_A \text{ is}$ variable depending upon conditions. Pulse curves are valid for duty cycles to 10% provided $T_{J(pk)} \leq 150^{\circ}C. T_{J(pk)}$ may be calculated from the data in Figure 19. At high case or ambient temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN**





NOTES

- DIMENSIONING AND TOLERANCING PER ANSI 1. Y14.5M, 1982. CONTROLLING DIMENSION: INCH
- 2. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF 3.
- BASE MATERIAL. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08. 4

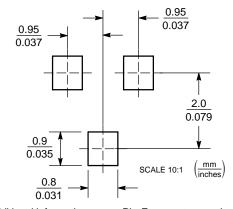
	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.89	1.00	1.11	0.035	0.040	0.044	
A1	0.01	0.06	0.10	0.001	0.002	0.004	
b	0.37	0.44	0.50	0.015	0.018	0.020	
С	0.09	0.13	0.18	0.003	0.005	0.007	
D	2.80	2.90	3.04	0.110	0.114	0.120	
E	1.20	1.30	1.40	0.047	0.051	0.055	
е	1.78	1.90	2.04	0.070	0.075	0.081	
L	0.10	0.20	0.30	0.004	0.008	0.012	
L1	0.35	0.54	0.69	0.014	0.021	0.029	
HE	2.10	2.40	2.64	0.083	0.094	0.104	

STYLE 6:

PIN 1. BASE 2. EMITTER

3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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